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(54) HEAT-RESISTANT INSULATED WIRE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a heat-resistant wire having excellent coating strength by forming a lower layer of specific polysilazane in a heat resistant insulation wire composed of base material, the lower layer coating the base material, and an upper layer coating the lower layer opposite to the base material.

SOLUTION: A lower layer is formed of polysilazane having repetition units -SiR<sub>1</sub>R<sub>2</sub>-NH- and -SiR<sub>3</sub>R<sub>4</sub>-Ar-SiR<sub>5</sub>R<sub>6</sub>-NH- [R<sub>1</sub>to<sub>6</sub> is H, (substitution) alkyl, alkenyl, alkoxy, phenyl, aryl, a group containing C; Ar is a group containing one or more of aromatic rings]. It is desirable that the repetition units of the polysilazane are -SiR<sub>1</sub>R<sub>2</sub>-NH-, -SiR<sub>3</sub>R<sub>4</sub>-Ar-SiR<sub>5</sub>R<sub>6</sub>-NH-, -SiR<sub>7</sub>R<sub>8</sub>-NH-Ar-NH- and -SiR<sub>9</sub>R<sub>10</sub>-Ar-NH-SiR<sub>11</sub>R<sub>12</sub>-NH-Ar-NH- (R<sub>7</sub>to<sub>12</sub> is R<sub>1</sub>). It is also desirable that the lower layer contains inorganic powder (for instance silicon dioxide) in addition to the polysilazane.

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